

Photoresist Patterning of Round Substrates

APPLICATIONS
NOTE #109



*Photoresist Pattern
on Internal Surface
of Round Substrate.
(Diameter=3 cm)*



*Photoresist Pattern on
External Surface of
Nickel Plated Substrate.*



*Magnified View (10X)
of Photoresist Pattern
on Nickel Plated
Round Substrate.*

Overview:

Standard positive photoresist is used to pattern highly curved, round substrates with the SF-100.

Process Flow:

1. Start with round substrate.
2. Coat with positive photoresist.
3. Expose patterns on the SF-100.
4. Develop photoresist.



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